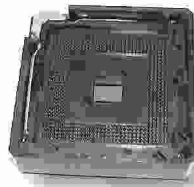


Specifications

Insulation Resistance:	1,000M min. at 100V DC
Dielectric Withstanding Voltage:	100V AC for 1 minute
Contact Resistance:	30m max. at 10mA/20mV max.
Operating Temperature Range:	-55°C to +150°C -40°C to +170°C
Contact Force:	13g per pin approx.
Operating Force:	3.2 Kg
Mating Cycles:	10,000 insertions

Materials and Finish

Housing: Polyetherimide (PEI), glass-filled
 Contacts: Beryllium Copper (BeCu)
 Plating: Gold over Nickel



Part Number (Details)

NP396 - 500 *

Series No.

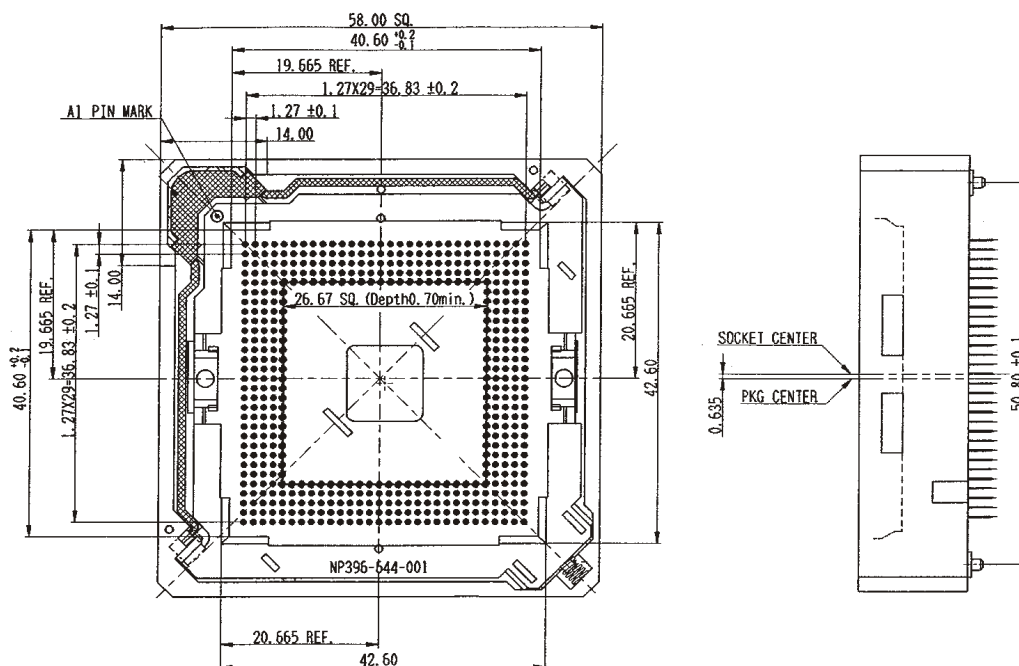
No. of Contact Pins

Design Number

Features

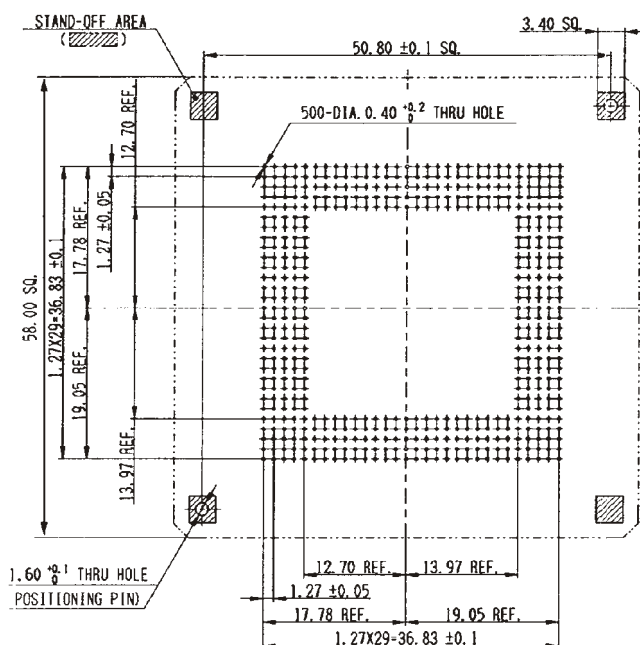
- ◇ Open top type sockets for BGA packages
- ◇ Coverless shrink version
- ◇ 2-point Tweezer Contact System

Outline Dimensions



Recommended PC Board Layout

Top View from Socket



Recommended PC Board Layout

